



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



## Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



---

**3-wire Serial EEPROM**  
**1K (128 x 8 or 64 x 16)**

---

**DATASHEET**

---

**Features**

---

- Low-voltage Operation
  - $V_{CC} = 1.8V$  to  $5.5V$
- User-selectable Internal Organization
  - 1K: 128 x 8 or 64 x 16
- 3-wire Serial Interface
- 2MHz Clock Rate (5V)
- Self-timed Write Cycle (5ms Max)
- High Reliability
  - Endurance: 1,000,000 Write Cycles
  - Data Retention: 100 Years
- 8-lead JEDEC SOIC, 8-lead TSSOP, 8-pad UDFN, 8-lead PDIP, and 8-ball VFBGA Packages

---

**Description**

---

The Atmel® AT93C46D provides 1,024 bits of Serial Electrically Erasable Programmable Read-Only Memory (EEPROM) organized as 64 words of 16 bits each (when the ORG pin is connected to  $V_{CC}$ ) and 128 words of 8 bits each (when the ORG pin is tied to ground). The device is optimized for use in many industrial and commercial applications where low-power and low-voltage operations are essential. The AT93C46D is available in space-saving 8-lead JEDEC SOIC, 8-lead TSSOP, 8-pad UDFN, 8-lead PDIP, and 8-ball VFBGA packages.

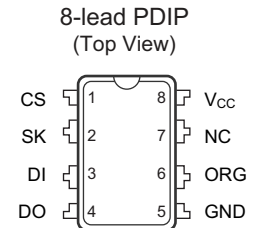
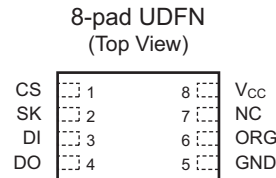
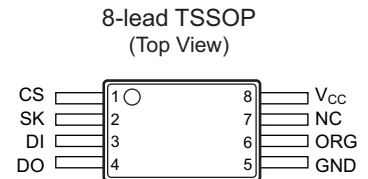
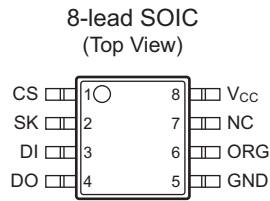
The AT93C46D is enabled through the Chip Select pin (CS) and accessed via a 3-wire serial interface consisting of Data Input (DI), Data Output (DO), and Shift Clock (SK). Upon receiving a Read instruction at DI, the address is decoded, and the data is clocked out serially on the DO pin. The write cycle is completely self-timed, and no separate erase cycle is required before Write. The write cycle is only enabled when the part is in the Erase/Write Enable state. When CS is brought high following the initiation of a write cycle, the DO pin outputs the Ready/Busy status of the part.

The AT93C46D operates from 1.8V to 5.5V.

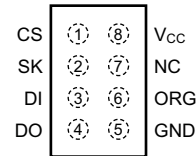
# 1. Pin Configurations and Pinouts

**Table 1-1. Pin Configurations**

Pin Name	Function
CS	Chip Select
SK	Serial Data Clock
DI	Serial Data Input
DO	Serial Data Output
GND	Ground
V <sub>CC</sub>	Power Supply
ORG	Internal Organization
NC	No Connect



8-ball VFBGA (Top View)



Note: Drawings are not to scale.

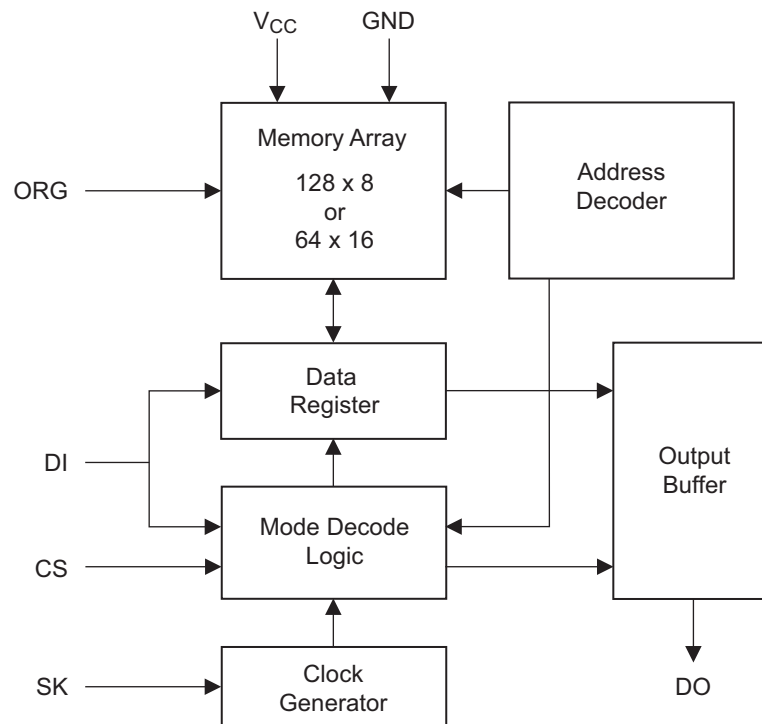
# 2. Absolute Maximum Ratings\*

Operating Temperature	-55°C to +125°C
Storage Temperature	-65°C to +150°C
Voltage on any pin with respect to ground	-1.0V to +7.0V
Maximum Operating Voltage	6.25V
DC Output Current	5.0mA

\*Notice: Stresses beyond those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

### 3. Block Diagram

Figure 3-1. Block Diagram



- Notes:
1. When the ORG pin is connected to  $V_{CC}$ , the x16 organization is selected. When it is connected to ground, the x8 organization is selected. If the ORG pin is left unconnected and the application does not load the input beyond the capability of the internal  $1M\Omega$  pull-up resistor, then the x16 organization is selected.
  2. If the x16 organization is the mode of choice and pin 6 (ORG) is left unconnected, Atmel recommends using AT93C46E device. For more details, see the AT93C46E datasheet.

## 4. Memory Organization

### 4.1 Pin Capacitance

**Table 4-1. Pin Capacitance<sup>(1)</sup>**

Applicable over recommended operating range from  $T_A = 25^\circ\text{C}$ ,  $f = 1.0\text{MHz}$ ,  $V_{CC} = 1.8\text{V}$  (unless otherwise noted).

Symbol	Test Conditions	Max	Units	Conditions
$C_{OUT}$	Output Capacitance (DO)	5	pF	$V_{OUT} = 0\text{V}$
$C_{IN}$	Input Capacitance (CS, SK, DI)	5	pF	$V_{IN} = 0\text{V}$

Note: 1. This parameter is characterized, and is not 100% tested.

### 4.2 DC Characteristics

**Table 4-2. DC Characteristics**

Applicable over recommended operating range from  $T_{AI} = -40^\circ\text{C}$  to  $+85^\circ\text{C}$ ,  $V_{CC} = 1.8\text{V}$  to  $5.5\text{V}$  (unless otherwise noted).

Symbol	Parameter	Test Condition	Min	Typ	Max	Unit
$V_{CC1}$	Supply Voltage		1.8		5.5	V
$V_{CC2}$	Supply Voltage		2.7		5.5	V
$V_{CC3}$	Supply Voltage		4.5		5.5	V
$I_{CC}$	Supply Current	$V_{CC} = 5.0\text{V}$	Read at 1.0MHz	0.5	2.0	mA
			Write at 1.0MHz	0.5	2.0	mA
$I_{SB1}$	Standby Current	$V_{CC} = 1.8\text{V}$		0.4	1.0	$\mu\text{A}$
$I_{SB2}$	Standby Current	$V_{CC} = 2.7\text{V}$		6.0	10.0	$\mu\text{A}$
$I_{SB3}$	Standby Current	$V_{CC} = 5.0\text{V}$		10.0	15.0	$\mu\text{A}$
$I_{IL}$	Input Leakage	$V_{IN} = 0\text{V}$ to $V_{CC}$		0.1	1.0	$\mu\text{A}$
$I_{OL}$	Output Leakage	$V_{IN} = 0\text{V}$ to $V_{CC}$		0.1	1.0	$\mu\text{A}$
$V_{IL1}^{(1)}$	Input Low Voltage	$2.7\text{V} \leq V_{CC} \leq 5.5\text{V}$	-0.6		0.8	V
$V_{IH1}^{(1)}$	Input High Voltage	$2.7\text{V} \leq V_{CC} \leq 5.5\text{V}$	2.0		$V_{CC} + 1$	V
$V_{IL2}^{(1)}$	Input Low Voltage	$1.8\text{V} \leq V_{CC} \leq 2.7\text{V}$	-0.6		$V_{CC} \times 0.3$	V
$V_{IH2}^{(1)}$	Input High Voltage	$1.8\text{V} \leq V_{CC} \leq 2.7\text{V}$	$V_{CC} \times 0.7$		$V_{CC} + 1$	V
$V_{OL1}$	Output Low Voltage	$2.7\text{V} \leq V_{CC} \leq 5.5\text{V}$			0.4	V
$V_{OH1}$	Output High Voltage	$2.7\text{V} \leq V_{CC} \leq 5.5\text{V}$	2.4			V
$V_{OL2}$	Output Low Voltage	$1.8\text{V} \leq V_{CC} \leq 2.7\text{V}$			0.2	V
$V_{OH2}$	Output High Voltage	$1.8\text{V} \leq V_{CC} \leq 2.7\text{V}$	$V_{CC} - 0.2$			V

Note: 1.  $V_{IL}$  min and  $V_{IH}$  max are reference only, and are not tested.

## 4.3 AC Characteristics

**Table 4-3. AC Characteristics**

Applicable over recommended operating range from  $T_{AI} = -40^{\circ}\text{C}$  to  $+85^{\circ}\text{C}$ ,  $V_{CC} =$  as specified,  $CL = 1$  TTL gate and  $100\text{pF}$  (unless otherwise noted).

Symbol	Parameter	Test Condition	Min	Typ	Max	Units
$f_{SK}$	SK Clock Frequency	$4.5\text{V} \leq V_{CC} \leq 5.5\text{V}$	0		2	MHz
		$2.7\text{V} \leq V_{CC} \leq 5.5\text{V}$	0		1	MHz
		$1.8\text{V} \leq V_{CC} \leq 5.5\text{V}$	0		250	kHz
$t_{SKH}$	SK High Time	$4.5\text{V} \leq V_{CC} \leq 5.5\text{V}$	250			ns
		$2.7\text{V} \leq V_{CC} \leq 5.5\text{V}$	250			ns
		$1.8\text{V} \leq V_{CC} \leq 5.5\text{V}$	1000			ns
$t_{SKL}$	SK Low Time	$4.5\text{V} \leq V_{CC} \leq 5.5\text{V}$	250			ns
		$2.7\text{V} \leq V_{CC} \leq 5.5\text{V}$	250			ns
		$1.8\text{V} \leq V_{CC} \leq 5.5\text{V}$	1000			ns
$t_{CS}$	Minimum CS Low Time	$4.5\text{V} \leq V_{CC} \leq 5.5\text{V}$	250			ns
		$2.7\text{V} \leq V_{CC} \leq 5.5\text{V}$	250			ns
		$1.8\text{V} \leq V_{CC} \leq 5.5\text{V}$	1000			ns
$t_{CSS}$	CS Setup Time	Relative to SK				
		$4.5\text{V} \leq V_{CC} \leq 5.5\text{V}$	50			ns
		$2.7\text{V} \leq V_{CC} \leq 5.5\text{V}$	50			ns
$t_{DIS}$	DI Setup Time	Relative to SK				
		$4.5\text{V} \leq V_{CC} \leq 5.5\text{V}$	100			ns
		$2.7\text{V} \leq V_{CC} \leq 5.5\text{V}$	100			ns
$t_{CSH}$	CS Hold Time	Relative to SK				
		$4.5\text{V} \leq V_{CC} \leq 5.5\text{V}$	0			ns
		$2.7\text{V} \leq V_{CC} \leq 5.5\text{V}$	400			ns
$t_{DIH}$	DI Hold Time	Relative to SK				
		$4.5\text{V} \leq V_{CC} \leq 5.5\text{V}$	100			ns
		$2.7\text{V} \leq V_{CC} \leq 5.5\text{V}$	400			ns
$t_{PD1}$	Output Delay to 1	AC Test				
		$4.5\text{V} \leq V_{CC} \leq 5.5\text{V}$			250	ns
		$2.7\text{V} \leq V_{CC} \leq 5.5\text{V}$			250	ns
$t_{PD0}$	Output Delay to 0	AC Test				
		$4.5\text{V} \leq V_{CC} \leq 5.5\text{V}$			250	ns
		$2.7\text{V} \leq V_{CC} \leq 5.5\text{V}$			250	ns
$t_{SV}$	CS to Status Valid	AC Test				
		$4.5\text{V} \leq V_{CC} \leq 5.5\text{V}$			250	ns
		$2.7\text{V} \leq V_{CC} \leq 5.5\text{V}$			250	ns
$t_{DF}$	CS to DO in High-impedance	AC Test CS = $V_{IL}$				
		$4.5\text{V} \leq V_{CC} \leq 5.5\text{V}$			100	ns
		$2.7\text{V} \leq V_{CC} \leq 5.5\text{V}$			250	ns
$t_{WP}$	Write Cycle Time	$1.8\text{V} \leq V_{CC} \leq 5.5\text{V}$	0.1	3	5	ms
Endurance <sup>(1)</sup>	5.0V, 25°C		1,000,000			Write Cycles

Note: 1. This parameter is characterized, and is not 100% tested.

## 5. Functional Description

The AT93C46D is accessed via a simple and versatile 3-wire serial communication interface. Device operation is controlled by seven instructions issued by the Host processor. A valid instruction starts with a rising edge of CS and consists of a Start bit (Logic 1), followed by the appropriate opcode, and the desired memory address location.

**Table 5-1. AT93C46D Instruction Set**

Instruction	SB	Opcode	Address		Data		Comments
			x8 <sup>(1)</sup>	x16 <sup>(1)</sup>	x8	x16	
READ	1	10	A <sub>6</sub> – A <sub>0</sub>	A <sub>5</sub> – A <sub>0</sub>			Reads data stored in memory at specified address.
EWEN	1	00	11XXXXXXXX	11XXXXXX			Write Enable must precede all programming modes.
ERASE	1	11	A <sub>6</sub> – A <sub>0</sub>	A <sub>5</sub> – A <sub>0</sub>			Erases memory location A <sub>N</sub> – A <sub>0</sub> .
WRITE	1	01	A <sub>6</sub> – A <sub>0</sub>	A <sub>5</sub> – A <sub>0</sub>	D <sub>7</sub> – D <sub>0</sub>	D <sub>15</sub> – D <sub>0</sub>	Writes memory location A <sub>N</sub> – A <sub>0</sub> .
ERAL	1	00	10XXXXXXXX	10XXXXXX			Erases all memory locations. Valid only at V <sub>CC3</sub> (Section 4.2, “DC Characteristics” on page 4).
WRAL	1	00	01XXXXXXXX	01XXXXXX	D <sub>7</sub> – D <sub>0</sub>	D <sub>15</sub> – D <sub>0</sub>	Writes all memory locations. Valid only at V <sub>CC3</sub> (Section 4.2).
EWDS	1	00	00XXXXXXXX	00XXXXXX			Disables all programming instructions.

Note: 1. The ‘X’ in the address field represent don’t care values, and must be clocked.

**READ:** The READ instruction contains the address code for the memory location to be read. After the instruction and address are decoded, data from the selected memory location is available at the Serial Output pin, DO. Output data changes are synchronized with the rising edges of the Serial Clock pin, SK. It should be noted that a dummy bit (Logic 0) precedes the 8-bit or 16-bit data output string.

**Erase/Write Enable (EWEN):** To ensure data integrity, the part automatically goes into the Erase/Write Disable (EWDS) state when power is first applied. An Erase/Write Enable (EWEN) instruction must be executed first before any programming instructions can be carried out.

Note: Once in the EWEN state, programming remains enabled until an EWDS instruction is executed, or V<sub>CC</sub> power is removed from the part.

**ERASE:** The ERASE instruction programs all bits in the specified memory location to the Logic 1 state. The self-timed erase cycle starts once the ERASE instruction and address are decoded. The DO pin outputs the Ready/Busy status of the part if CS is brought high after being kept low for a minimum of t<sub>CS</sub>. A Logic 1 at the DO pin indicates that the selected memory location has been erased, and the part is ready for another instruction.

**WRITE:** The WRITE instruction contains the 8-bits or 16-bits of data to be written into the specified memory location. The self-timed programming cycle,  $t_{WP}$ , starts after the last bit of data is received at Serial Data Input pin DI. The DO pin outputs the Ready/Busy status of the part if CS is brought high after being kept low for a minimum of  $t_{CS}$ . A Logic 0 at DO indicates that programming is still in progress. A Logic 1 indicates that the memory location at the specified address has been written with the data pattern contained in the instruction, and the part is ready for further instructions. A Ready/Busy status cannot be obtained if CS is brought high after the end of the self-timed programming cycle,  $t_{WP}$ .

**Erase All (ERAL):** The Erase All (ERAL) instruction programs every bit in the Memory Array to the Logic 1 state and is primarily used for testing purposes. The DO pin outputs the Ready/Busy status of the part if CS is brought high after being kept low for a minimum of  $t_{CS}$ . The ERAL instruction is valid only at  $V_{CC} = 5.0V \pm 10\%$  (Section 4.2, “DC Characteristics” on page 4).

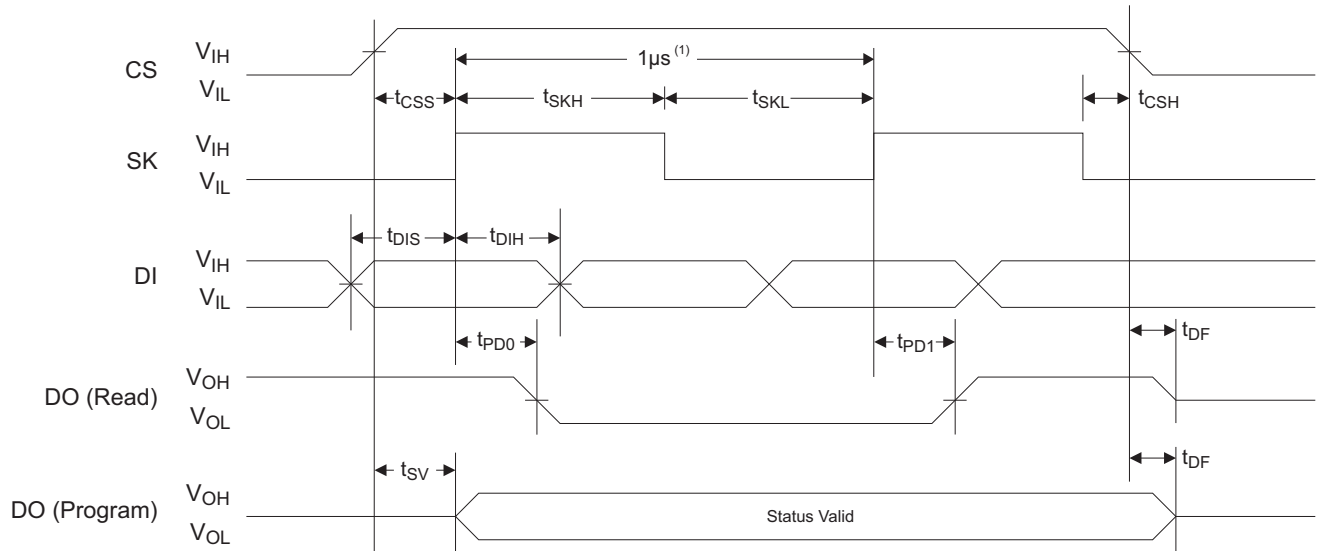
**Write All (WRAL):** The Write All (WRAL) instruction programs all memory locations with the data patterns specified in the instruction. The DO pin outputs the Ready/Busy status of the part if CS is brought high after being kept low for a minimum of  $t_{CS}$ . The WRAL instruction is valid only at  $V_{CC} = 5.0V \pm 10\%$  (Section 4.2).

**Erase/Write Disable (EWDS):** To protect against accidental data disturbance, the Erase/Write Disable (EWDS) instruction disables all programming modes and should be executed after all programming operations. The operation of the Read instruction is independent of both the EWEN and EWDS instructions and can be executed at any time.



## 6. Timing Diagrams

Figure 6-1. Synchronous Data Timing

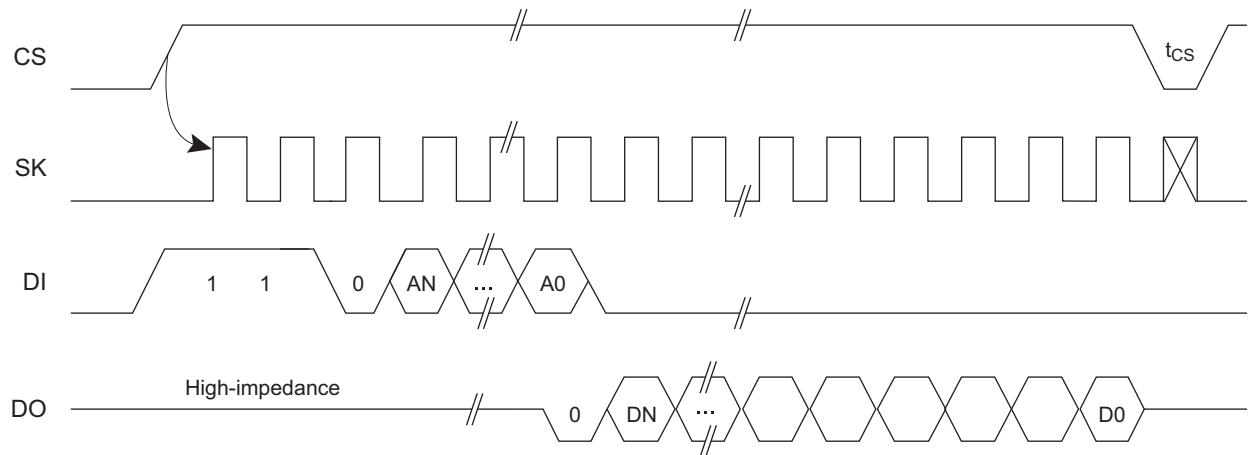


Note: 1. This is the minimum SK period.

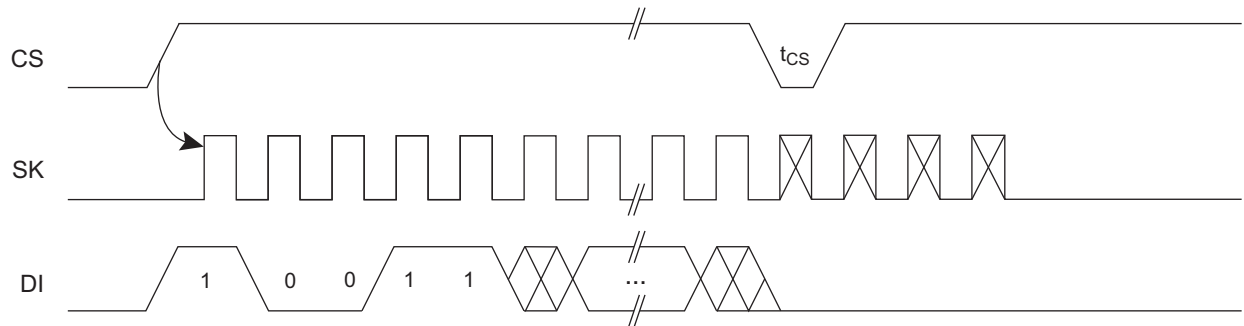
Table 6-1. Organization Key for Timing Diagrams

I/O	AT93C46D (1K)	
	x8	x16
$A_N$	$A_6$	$A_5$
$D_N$	$D_7$	$D_{15}$

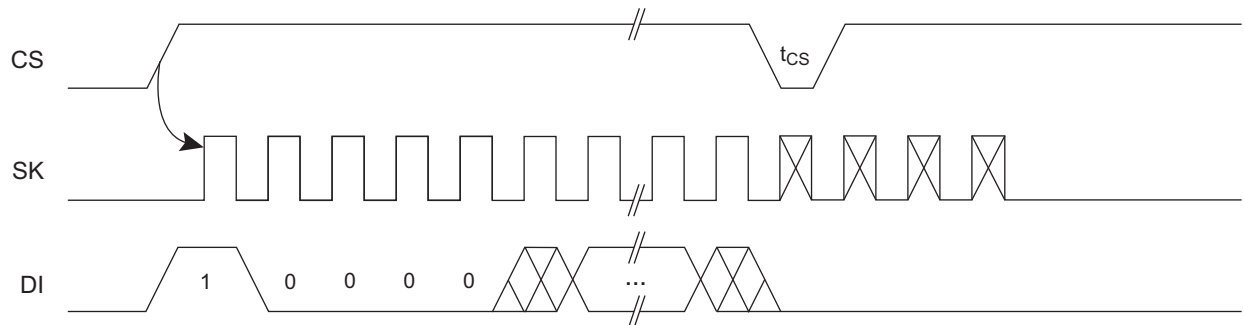
**Figure 6-2. READ Timing**



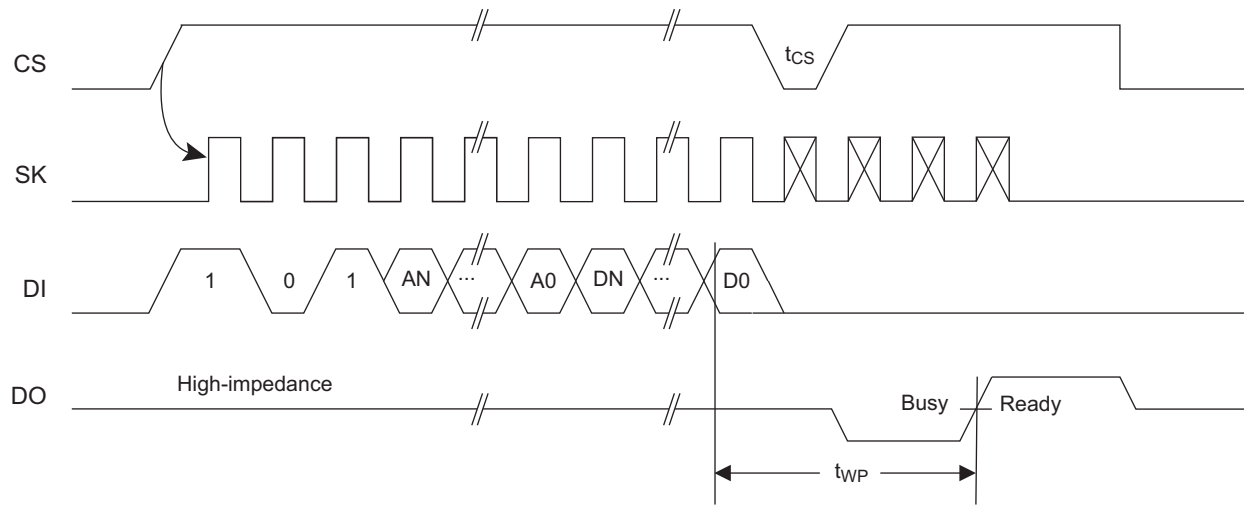
**Figure 6-3. EWEN Timing**



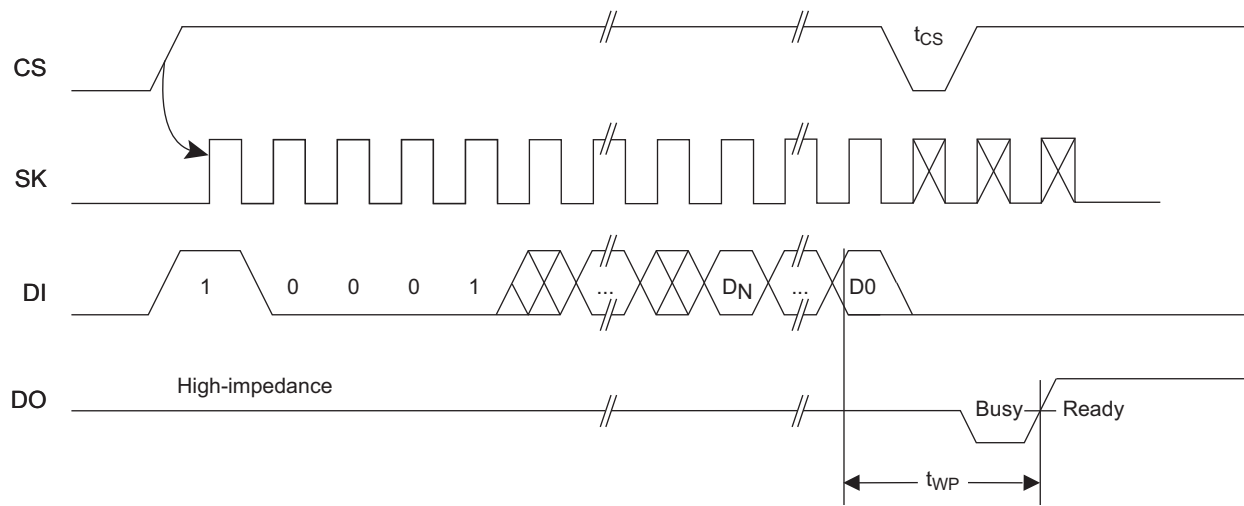
**Figure 6-4. EWDS Timing**



**Figure 6-5. WRITE Timing**

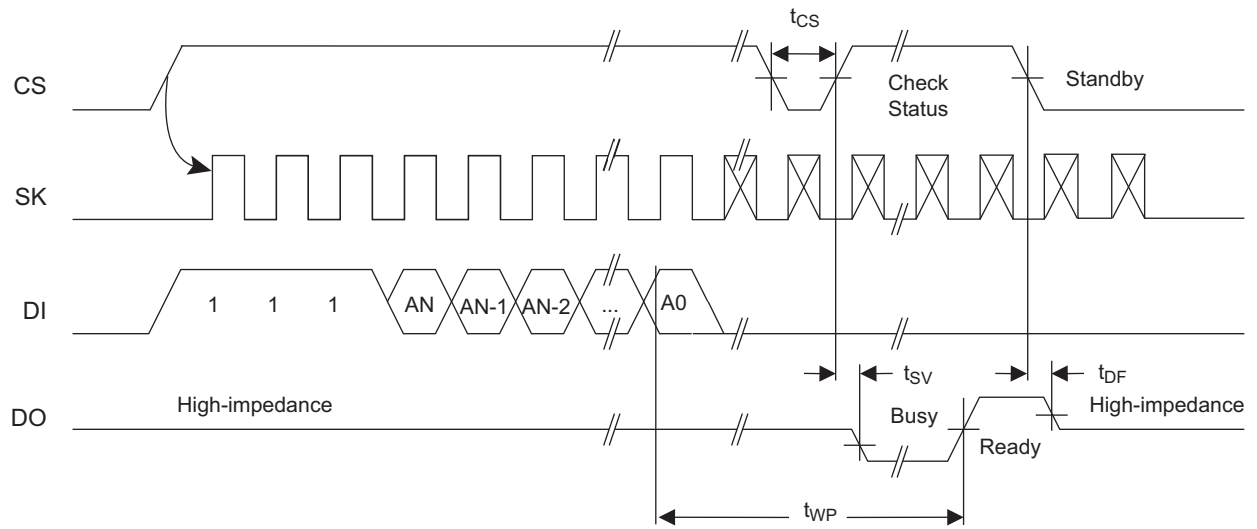


**Figure 6-6. WRAL Timing<sup>(1)</sup>**

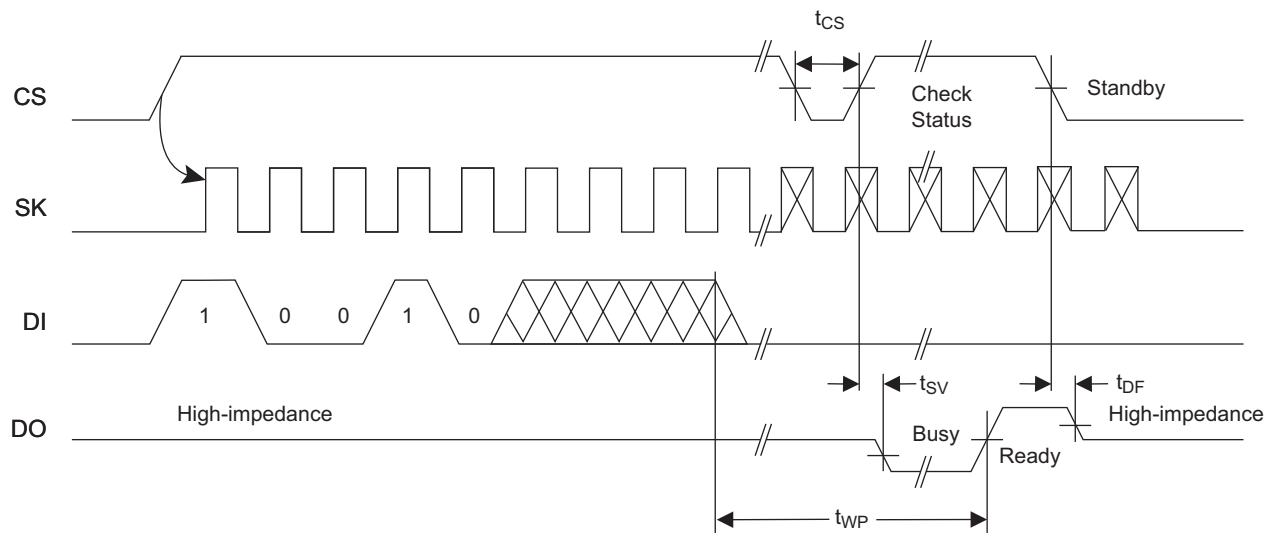


Note: 1. Valid only at  $V_{CC3}$  (Section 4.2, "DC Characteristics" on page 4).

**Figure 6-7. ERASE Timing**

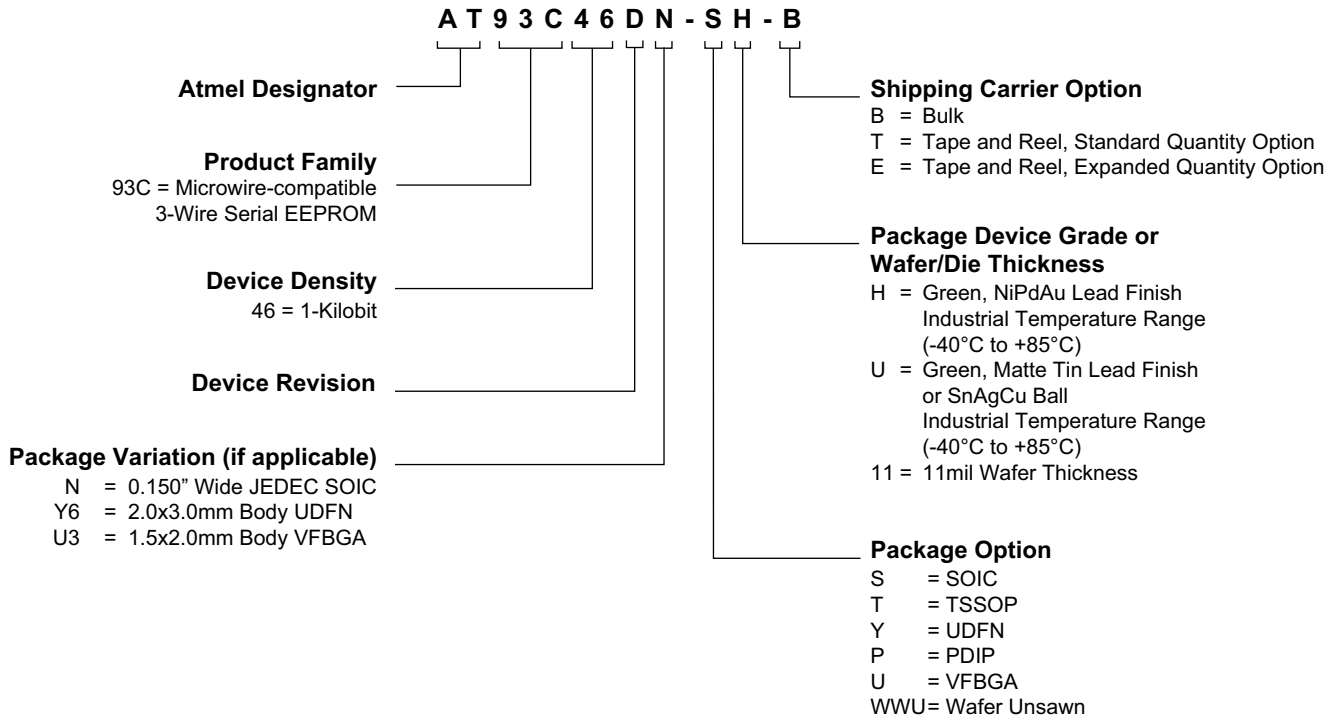


**Figure 6-8. ERAL Timing<sup>(1)</sup>**



Note: 1. Valid only at  $V_{CC3}$  (Section 4.2, "DC Characteristics" on page 4).

## 7. Ordering Code Detail



## 8. Ordering Information

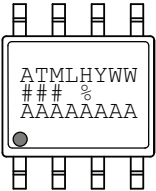
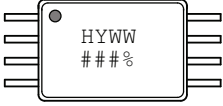
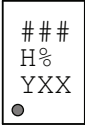


Atmel Ordering Code	Lead Finish	Package	Delivery Information		Operation Range
			Form	Quantity	
AT93C46DN-SH-B	NiPdAu (Lead-free/Halogen-free)	8S1	Bulk (Tubes)	100 per Tube	Industrial Temperature (-40°C to 85°C)
AT93C46DN-SH-T			Tape and Reel	4,000 per Reel	
AT93C46D-TH-B		8X	Bulk (Tubes)	100 per Tube	
AT93C46D-TH-T			Tape and Reel	5,000 per Reel	
AT93C46DY6-YH-T		8MA2	Tape and Reel	5,000 per Reel	
AT93C46DY6-YH-E			Tape and Reel	15,000 per Reel	
AT93C46D-PU	Matte Tin (Lead-free/Halogen free)	8P3	Bulk (Tubes)	50 per Tube	
AT93C46DU3-UU-T	SnAgCu (Lead-free/Halogen-free)	8U3-1	Tape and Reel	5,000 per Reel	
AT93C46D-W-11 <sup>(1)</sup>	N/A	Wafer Sale	Note 1		

Note: 1. For wafer sales, please contact Atmel sales. Bumped die available upon request.

Package Type	
8S1	8-lead, 0.150" wide, Plastic Gull Wing, Small Outline (JEDEC SOIC)
8X	8-lead, 0.170" wide, Thin Shrink Small Outline (TSSOP)
8MA2	8-pad, 2.00mm x 3.00mm body, 0.50mm pitch, Ultra Thin Dual No Lead (UDFN)
8P3	8-lead, 0.300" wide body, Plastic Dual In-line Package (PDIP)
8U3-1	8-ball, 1.50mm x 2.00mm body, 0.50mm pitch, Small Die Ball Grid Array (VFBGA)

## 9. Part Markings

### AT93C46D: Package Marking Information


<p>8-lead SOIC</p> 	<p>8-lead TSSOP</p>  <p><i>Note: Lot Number and location of assembly and on the bottom side of the package.</i></p>	<p>8-pad UDFN</p> <p>2.0 x 3.0 mm Body</p> 
<p>8-lead PDIP</p> 	<p>8-ball VFBGA</p> <p>1.5 x 2.0 mm Body</p> 	

Note 1: ● designates pin 1

Note 2: Package drawings are not to scale

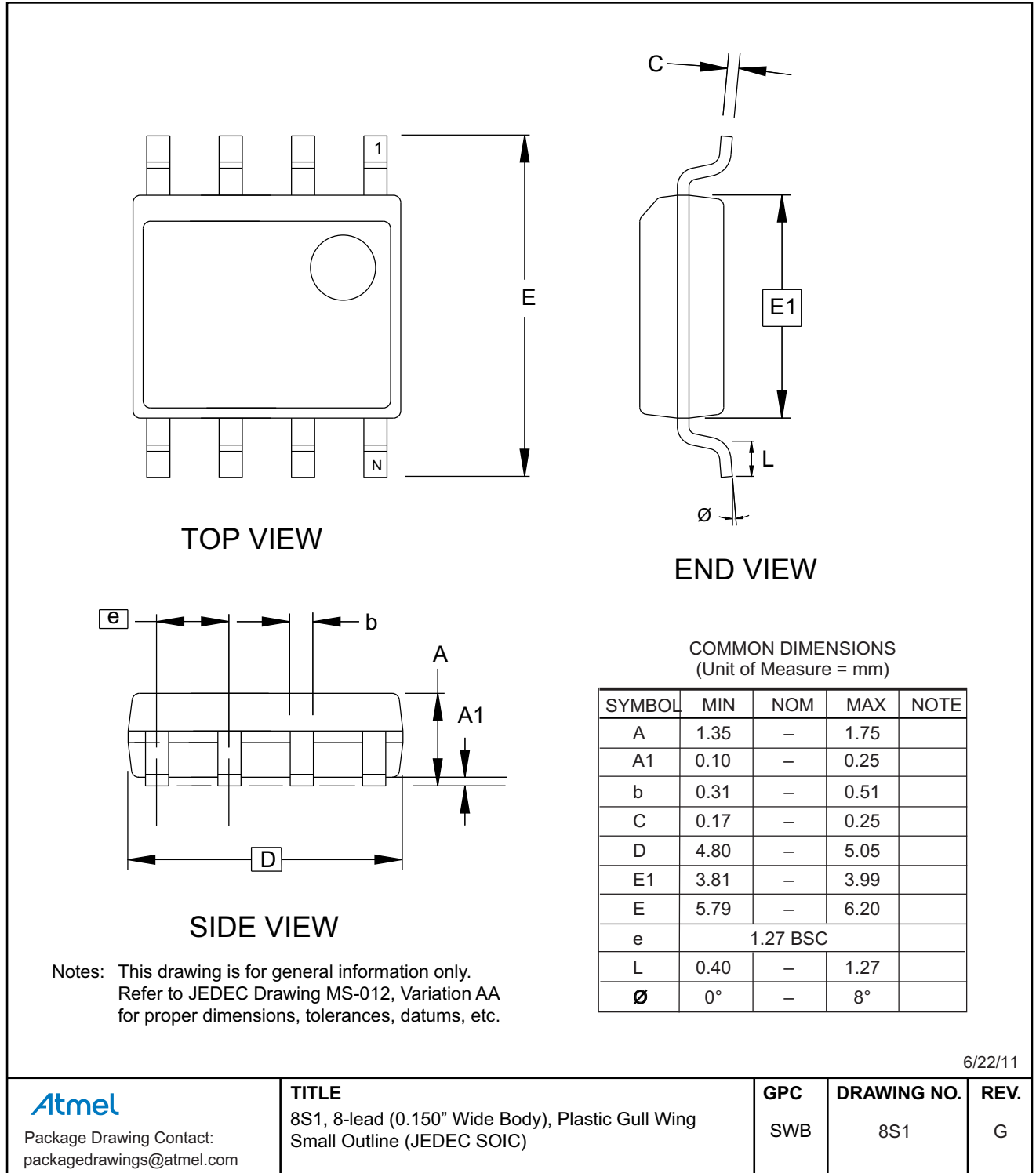
<b>Catalog Number Truncation</b>			
AT93C46D		Truncation Code ###: 46D	
<b>Date Codes</b>			<b>Voltages</b>
Y = Year	M = Month	WW = Work Week of Assembly	% = Minimum Voltage
4: 2014    8: 2018	A: January	02: Week 2	1: 1.8V min
5: 2015    9: 2019	B: February	04: Week 4	
6: 2016    0: 2020	...	...	
7: 2017    1: 2021	L: December	52: Week 52	
<b>Country of Assembly</b>		<b>Lot Number</b>	<b>Grade/Lead Finish Material</b>
@ = Country of Assembly		AAA...A = Atmel Wafer Lot Number	H: Industrial/NiPdAu U: Industrial/Matte Tin/SnAgCu
<b>Trace Code</b>			<b>Atmel Truncation</b>
XX = Trace Code (Atmel Lot Numbers Correspond to Code) Example: AA, AB.... YZ, ZZ			AT: Atmel ATM: Atmel ATML: Atmel

6/11/14

 <p>Package Mark Contact: DL-CSO-Assy_eng@atmel.com</p>	<p><b>TITLE</b></p> <p>93C46DSM, AT93C46D Package Marking Information</p>	<p><b>DRAWING NO.</b></p> <p>93C46DSM</p>	<p><b>REV.</b></p> <p>A</p>

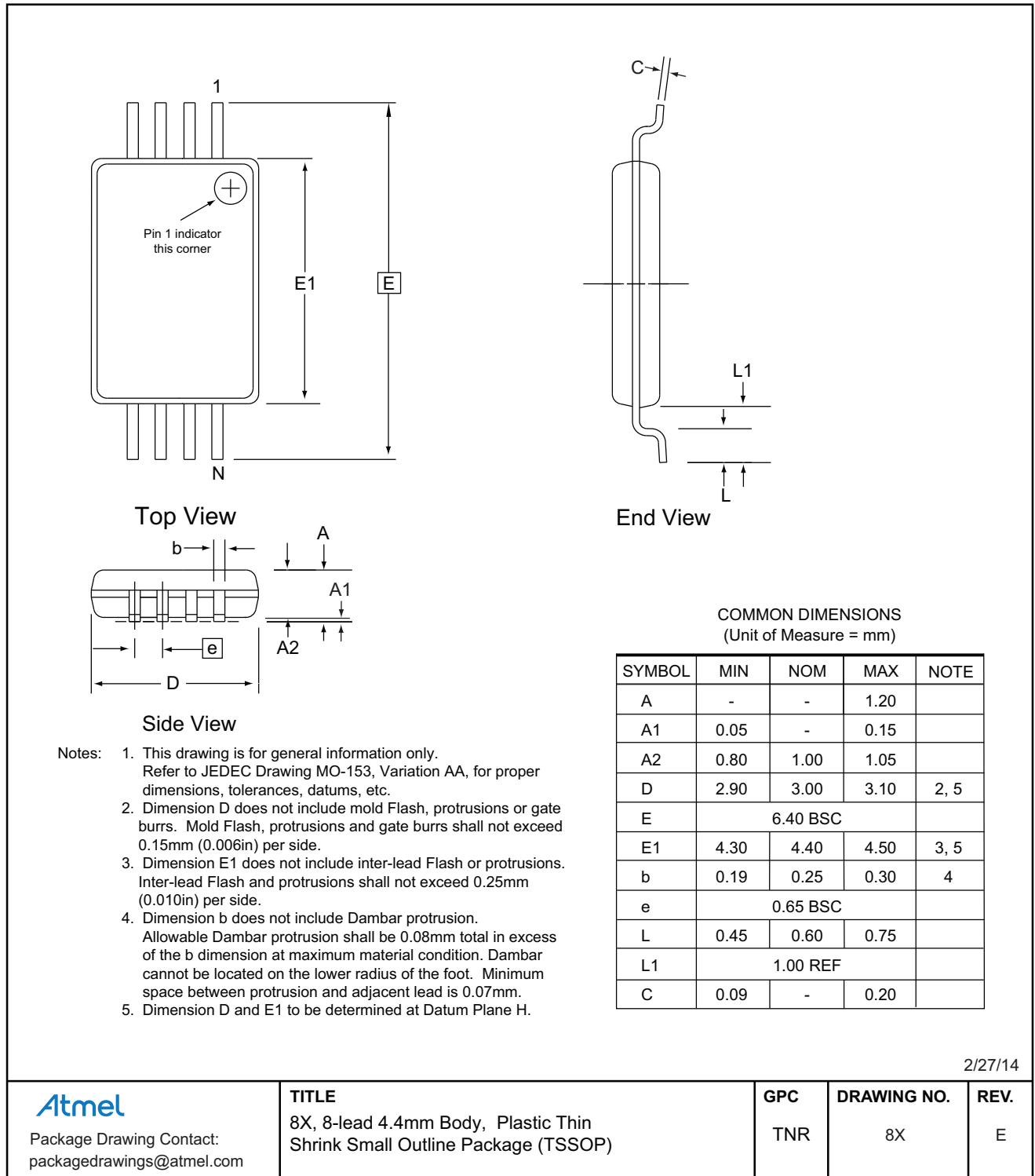
## 10. Packaging Information

### 10.1 8S1 — 8-lead JEDEC SOIC

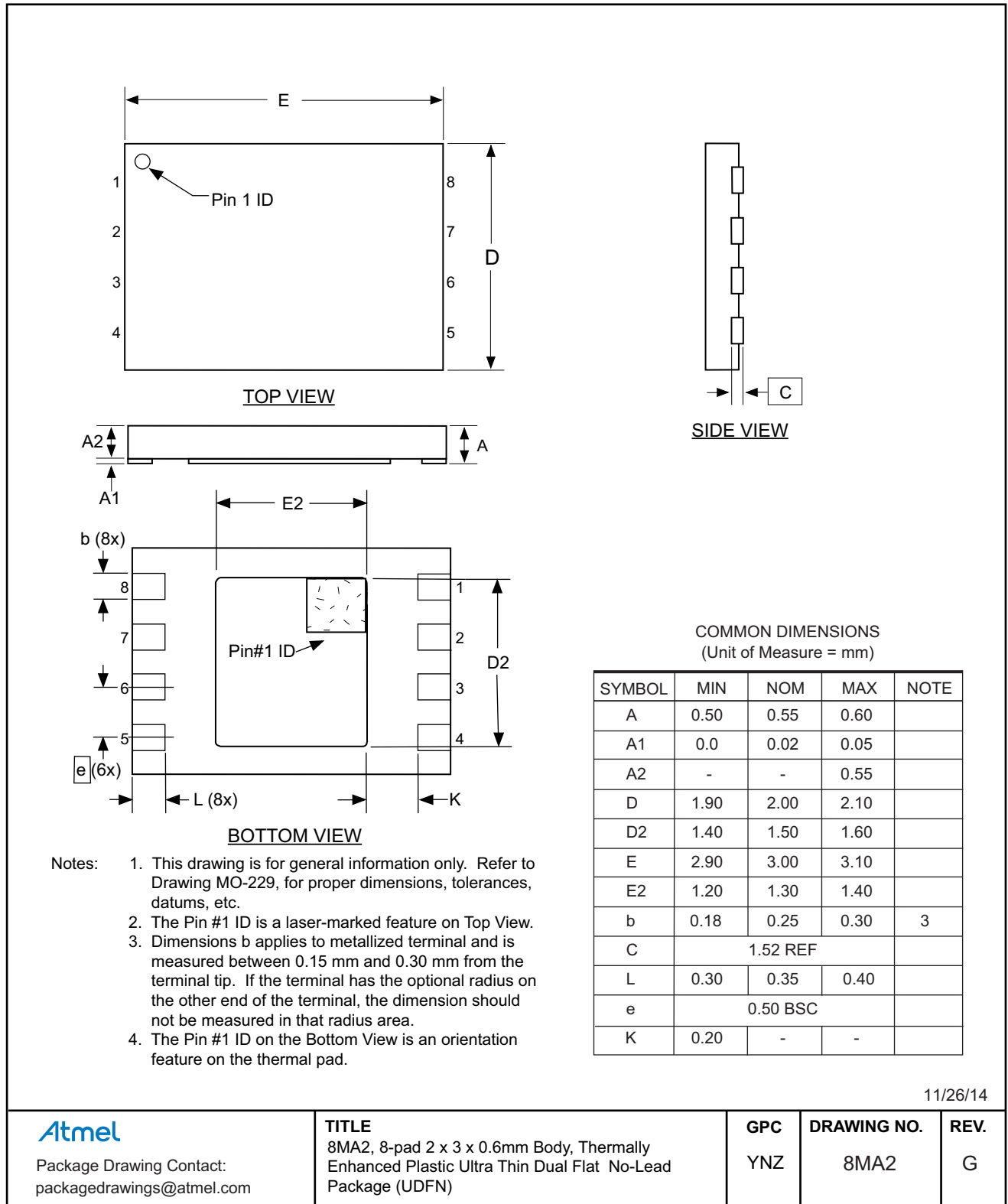




## 10.2 8X — 8-lead TSSOP



### 10.3 8MA2 — 8-pad UDFN



11/26/14

**Atmel**

Package Drawing Contact:  
packagedrawings@atmel.com

**TITLE**

8MA2, 8-pad 2 x 3 x 0.6mm Body, Thermally Enhanced Plastic Ultra Thin Dual Flat No-Lead Package (UDFN)

**GPC**

YNZ

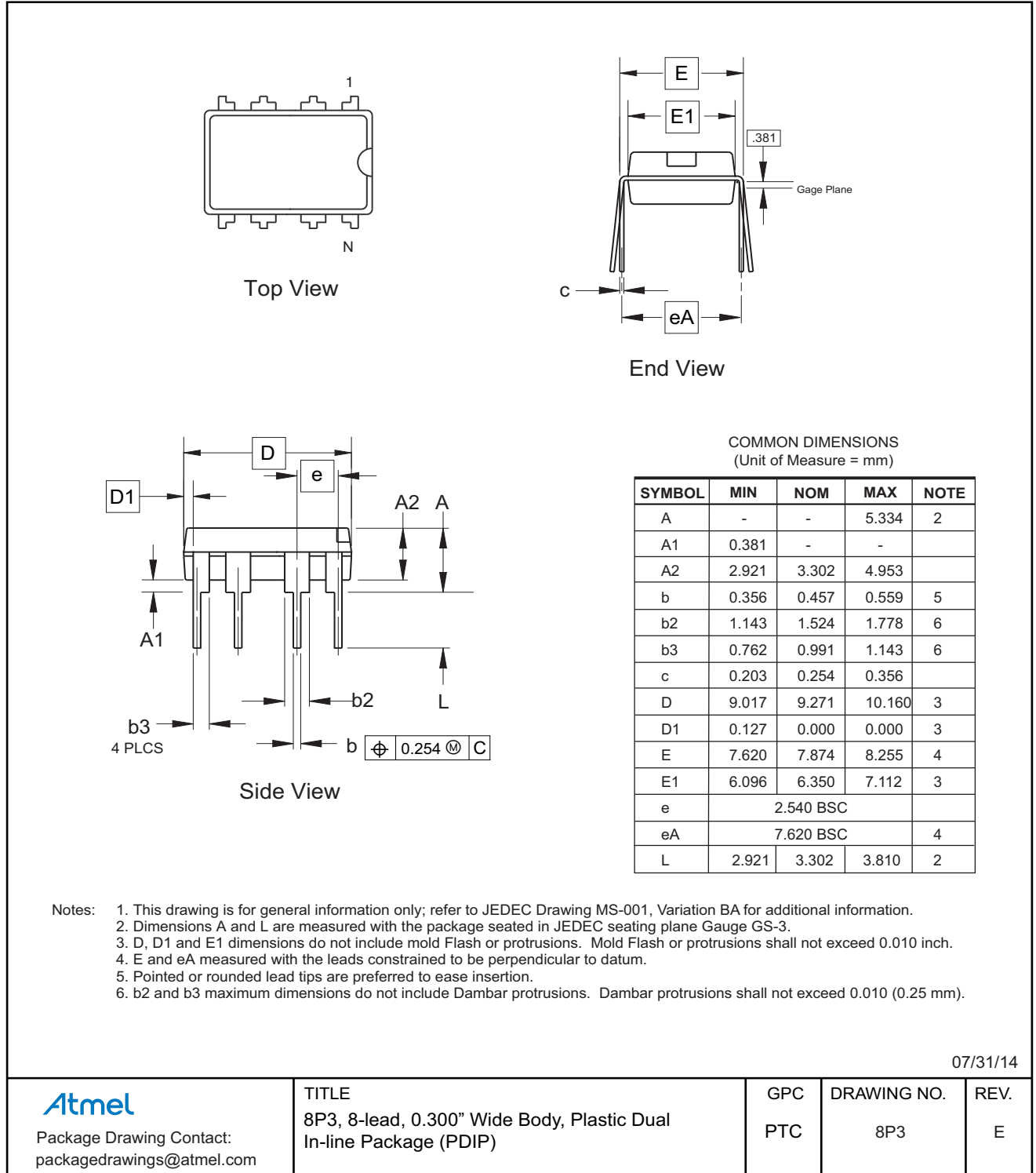
**DRAWING NO.**

8MA2

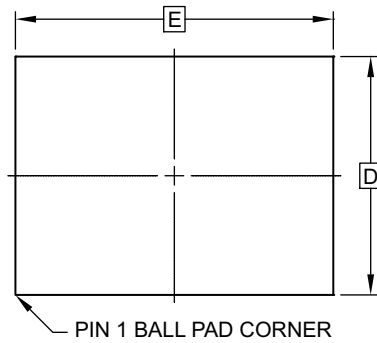
**REV.**

G

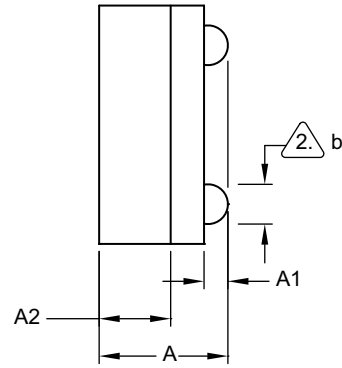
## 10.4 8P3 — 8-lead PDIP



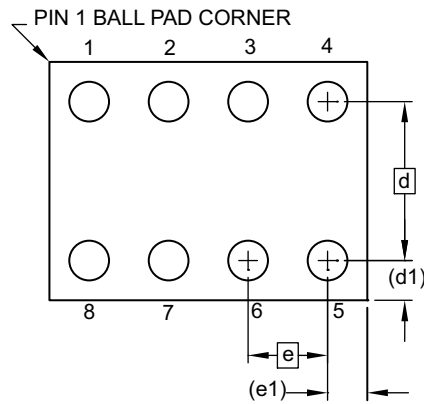
## 10.5 8U3-1 — 8-ball VFBGA



TOP VIEW



SIDE VIEW



BOTTOM VIEW  
8 SOLDER BALLS


**Notes:**

1. This drawing is for general information only.
2. Dimension 'b' is measured at maximum solder ball diameter.
3. Solder ball composition shall be 95.5Sn-4.0Ag-.5Cu.

COMMON DIMENSIONS  
(Unit of Measure - mm)

SYMBOL	MIN	NOM	MAX	NOTE
A	0.73	0.79	0.85	
A1	0.09	0.14	0.19	
A2	0.40	0.45	0.50	
b	0.20	0.25	0.30	2
D	1.50 BSC			
E	2.0 BSC			
e	0.50 BSC			
e1	0.25 REF			
d	1.00 BSC			
d1	0.25 REF			

6/11/13

 Package Drawing Contact: packagedrawings@atmel.com	TITLE 8U3-1, 8-ball, 1.50mm x 2.00mm body, 0.50mm pitch, Very Thin, Fine-Pitch Ball Grid Array Package (VFBGA)	GPC	DRAWING NO.	REV.
		GXU	8U3-1	F

## 11. Revision History

Revision No.	Date	Comments
5193H	01/2015	Added the UDFN expanded quantity option and the ordering information section. Updated the 8MA2 and 8P3 package drawings.
5193G	08/2014	Updated package drawings, template, logos, and disclaimer page.
5193F	01/2008	Removed the 'preliminary' status.
5193E	11/2007	Modified the 'max' value in AC Characteristics table.
5193D	08/2007	Moved Pinout figure. Added new feature for Die Sales. Modified Ordering Information table layout. Modified Park Marking Schemes.
5193C	06/2007	Updated to new template. Added Product Markup Scheme. Added Technical email contact. Corrected Figures 4 and 5.
5193B	02/2007	Added 'Ultra Thin' description to 8-lead Mini-MAP package.
5193A	01/2007	Initial document release.

Atmel®, Atmel logo and combinations thereof, Enabling Unlimited Possibilities®, and others are registered trademarks or trademarks of Atmel Corporation in U.S. and other countries. Other terms and product names may be trademarks of others.

DISCLAIMER: The information in this document is provided in connection with Atmel products. No license, express or implied, by estoppel or otherwise, to any intellectual property right is granted by this document or in connection with the sale of Atmel products. EXCEPT AS SET FORTH IN THE ATMEL TERMS AND CONDITIONS OF SALES LOCATED ON THE ATMEL WEBSITE, ATMEL ASSUMES NO LIABILITY WHATSOEVER AND DISCLAIMS ANY EXPRESS, IMPLIED OR STATUTORY WARRANTY RELATING TO ITS PRODUCTS INCLUDING, BUT NOT LIMITED TO, THE IMPLIED WARRANTY OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE, OR NON-INFRINGEMENT. IN NO EVENT SHALL ATMEL BE LIABLE FOR ANY DIRECT, INDIRECT, CONSEQUENTIAL, PUNITIVE, SPECIAL OR INCIDENTAL DAMAGES (INCLUDING, WITHOUT LIMITATION, DAMAGES FOR LOSS AND PROFITS, BUSINESS INTERRUPTION, OR LOSS OF INFORMATION) ARISING OUT OF THE USE OR INABILITY TO USE THIS DOCUMENT, EVEN IF ATMEL HAS BEEN ADVISED OF THE POSSIBILITY OF SUCH DAMAGES. Atmel makes no representations or warranties with respect to the accuracy or completeness of the contents of this document and reserves the right to make changes to specifications and products descriptions at any time without notice. Atmel does not make any commitment to update the information contained herein. Unless specifically provided otherwise, Atmel products are not suitable for, and shall not be used in, automotive applications. Atmel products are not intended, authorized, or warranted for use as components in applications intended to support or sustain life.

SAFETY-CRITICAL, MILITARY, AND AUTOMOTIVE APPLICATIONS DISCLAIMER: Atmel products are not designed for and will not be used in connection with any applications where the failure of such products would reasonably be expected to result in significant personal injury or death ("Safety-Critical Applications") without an Atmel officer's specific written consent. Safety-Critical Applications include, without limitation, life support devices and systems, equipment or systems for the operation of nuclear facilities and weapons systems. Atmel products are not designed nor intended for use in military or aerospace applications or environments unless specifically designated by Atmel as military-grade. Atmel products are not designed nor intended for use in automotive applications unless specifically designated by Atmel as automotive-grade.